

IN THE CLAIMS

Claims 1-12 and 16-21 previously canceled.

13. (Previously Amended) A method for coupling an IC to a supporting surface comprising:
providing an IC;
providing a supporting surface to which the IC is to be mechanically and electrically bonded;
providing a pre-form assembly comprising a base layer and a sacrificial layer, the base layer comprising a thermosetting material or a thermoplastic material and wire or solder paste through conductors;
applying the pre-form assembly to either the IC or supporting surface;
peeling away the sacrificial layer;
sandwiching the base layer between the IC and the supporting surface; and
curing the base layer.
14. (Original) The method of claim 13 wherein providing the preform assembly comprises:
providing a sacrificial layer;
coating the sacrificial later with a release coating;
applying a thermosetting material on top of the release coating;
curing the thermosetting material to form a B-stage layer; and
inserting through conductors into the thermosetting material.
15. (Original) The method of claim 14 wherein the step of inserting through conductors into the thermosetting material comprises either piercing wires into the thermosetting

material, or lasing or drilling and subsequently filling holes in the thermosetting material with a solder paste.

22. (Currently Amended) The method of claim 14 wherein the release coating at least partially comprises silicon, polytetrafluoroethylene Teflon®, or graphite release agents.
23. (Currently Amended) The method of claim 13 wherein the base layer further comprises a fine mesh fiber material impregnated with ~~a thermoset~~ the thermosetting material, and the fine mesh fiber is thermally conductive.
24. (Currently Amended) The method of claim 13 wherein the base layer further comprises a fine mesh fiber material impregnated with ~~a thermoset~~ the thermosetting material and the fine mesh fiber is electrically non-conductive.
25. (Currently Amended) The method of claim 13 wherein the base layer further comprises a ~~thermoset~~ the thermosetting material intermixed with a particle filler.
26. (Previously Added) The method of claim 25 wherein the particle filler is thermally conductive.
27. (Previously Added) The method of claim 25 wherein the particle filler is electrically non-conductive.